

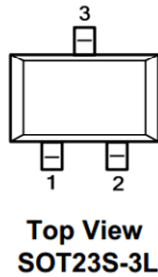
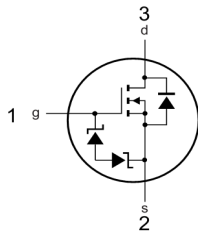
## N-Channel 50V MOSFET

### Features:

- Surface-mounted package
- High Density Cell Design
- Low Threshold Voltage
- Halogen free
- ESD protected 1500V

### Application

- DC-DC
- Portable appliance
- Power management



$B_{VDSS} = 50V$ , $R_{DS(ON)} < 10\Omega @ V_{GS} = 2.75V$ $R_{DS(ON)} < 3.5\Omega @ V_{GS} = 5.0V$ $I_D = 200mA$
---

### Absolute Maximum Ratings (T<sub>A</sub>=25°C Unless Otherwise Noted)

Parameter	Symbol	BSS138K	Unit
	Marking	J2	
Drain-Source Voltage	V <sub>DSS</sub>	50	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	200	mA
Pulsed Drain Current (t <sub>p</sub> ≤ 10us)	I <sub>DM</sub>	800	mA
Power Dissipation	P <sub>D</sub>	225	mW
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C

### Thermal Characteristics

Symbol	Characteristic	Max.	Units
R <sub>θJA</sub>	Junction-to-Ambient	556	°C/W

**N-Channel 50V MOSFET**

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  Unless Otherwise Specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static <sup>(1)</sup>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	50	--	--	V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=1mA$	0.5	--	1.5	V
$I_{GSS}$	Gate-Body Leakage	$V_{DS}=0V, V_{GS}=\pm 20V$	--	--	$\pm 10$	$\mu A$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=25V, V_{GS}=0V$	--	--	0.1	$\mu A$
		$V_{DS}=50V, V_{GS}=0V$	--	--	0.5	
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=2.75V, I_D=200mA$	--	--	10	$\Omega$
		$V_{GS}=5.0V, I_D=200mA$	--	--	3.5	$\Omega$
$g_{FS}$	Forward Transconductance	$I_D=200mA, V_{DS}=25V$	100	--	--	mmhos
Dynamic <sup>(2)</sup>						
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1.0MHz$	--	40	50	$\mu F$
$C_{oss}$	Output Capacitance		--	12	25	
$C_{rss}$	Reverse Transfer Capacitance		--	3.5	5.0	
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=30V, I_D=0.2A$	--	5	20	nSs
$t_{d(off)}$	Turn-Off Delay Time		--	5	20	

Note :

- (1) Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- (2) Switching characteristics are independent of operating junction temperature.

N-Channel 50V MOSFET

TYPICAL ELECTRICAL CHARACTERISTICS

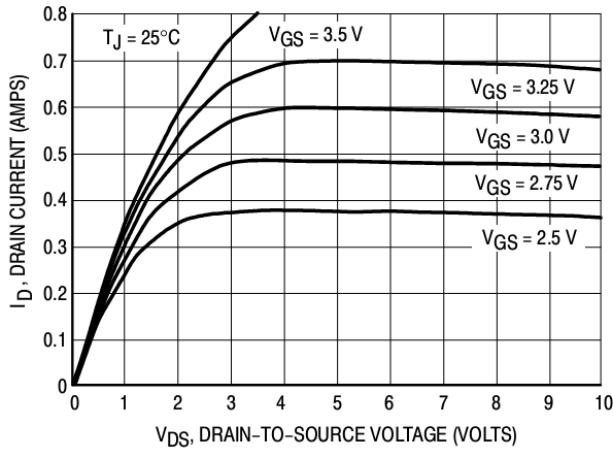


Figure 1. On-Region Characteristics

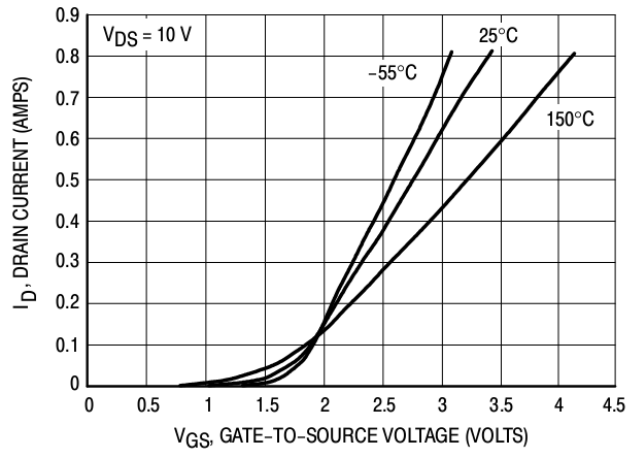


Figure 2. Transfer Characteristics

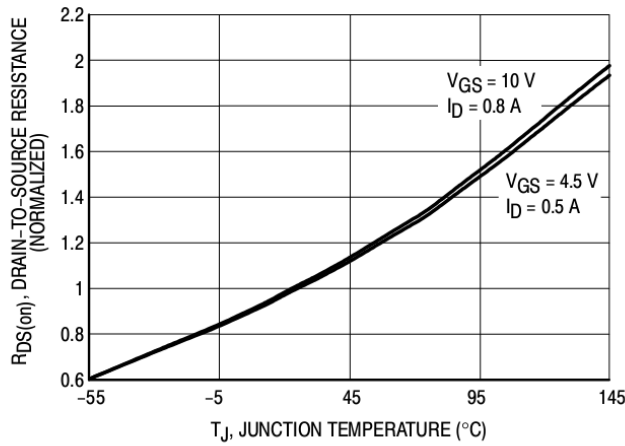


Figure 3. On-Resistance Variation with Temperature

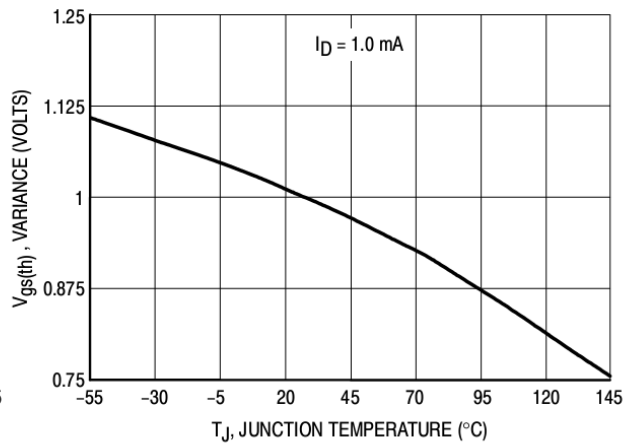


Figure 4. Threshold Voltage Variation with Temperature

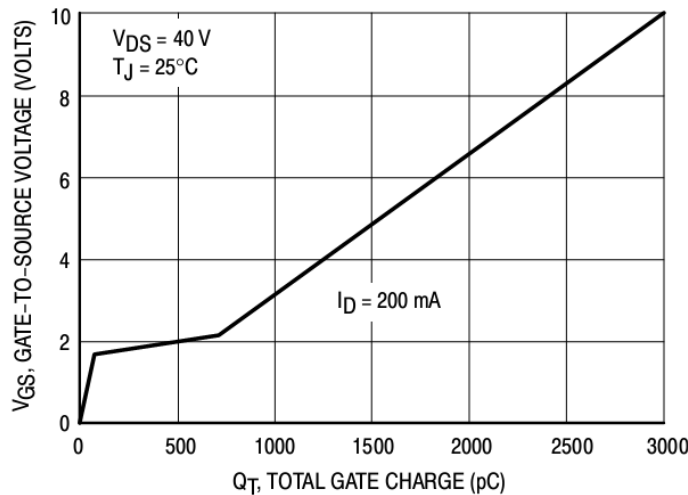


Figure 5. Gate Charge

N-Channel 50V MOSFET

TYPICAL ELECTRICAL CHARACTERISTICS

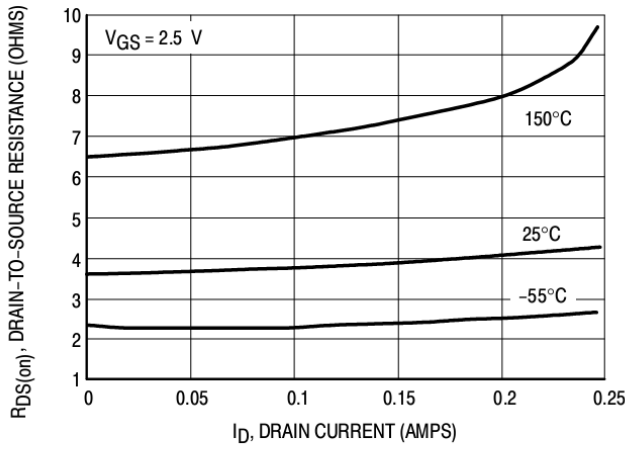


Figure 6. On-Resistance versus Drain Current

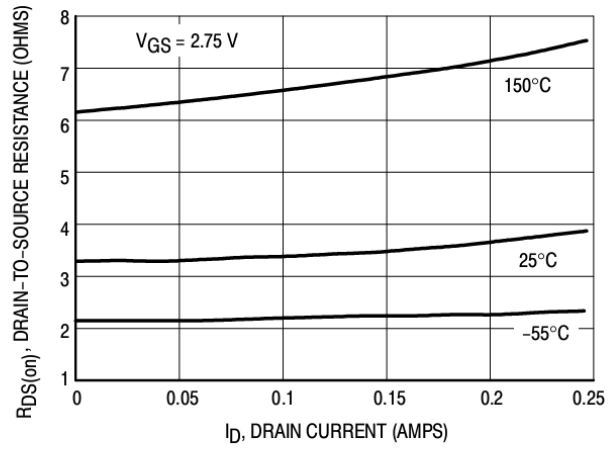


Figure 7. On-Resistance versus Drain Current

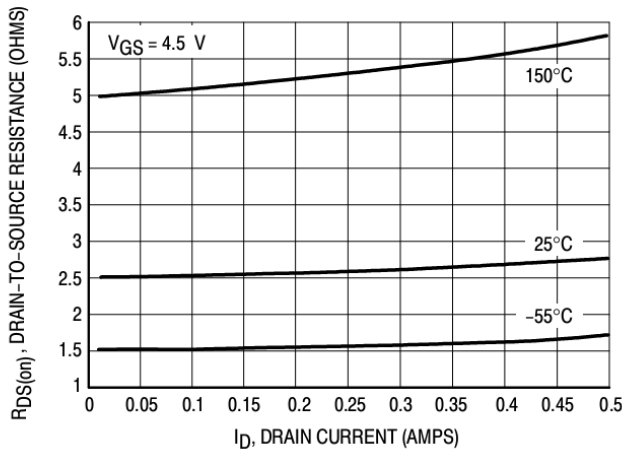


Figure 8. On-Resistance versus Drain Current

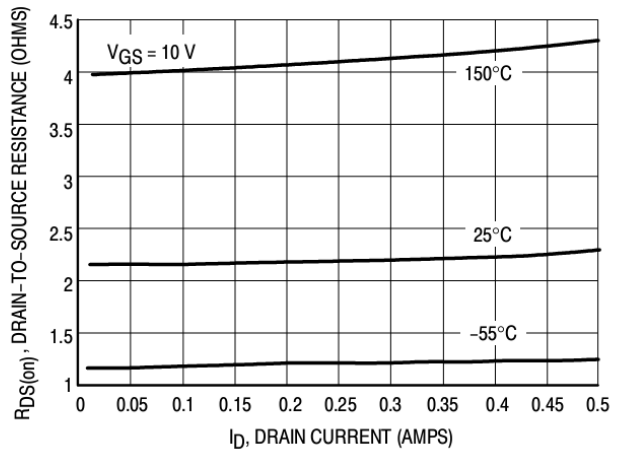


Figure 9. On-Resistance versus Drain Current

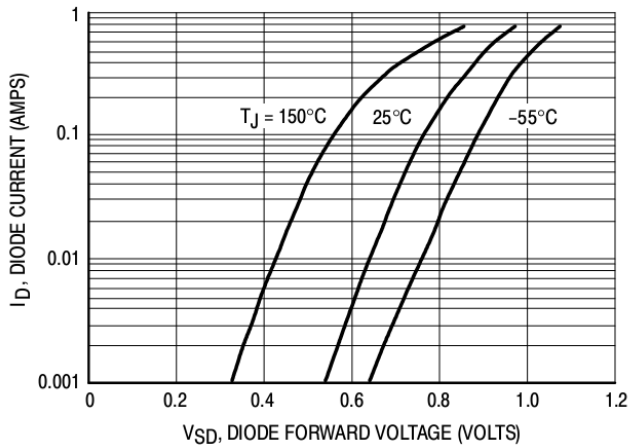


Figure 10. Body Diode Forward Voltage

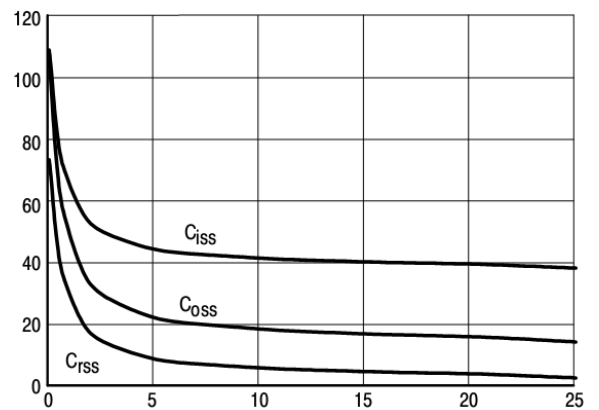
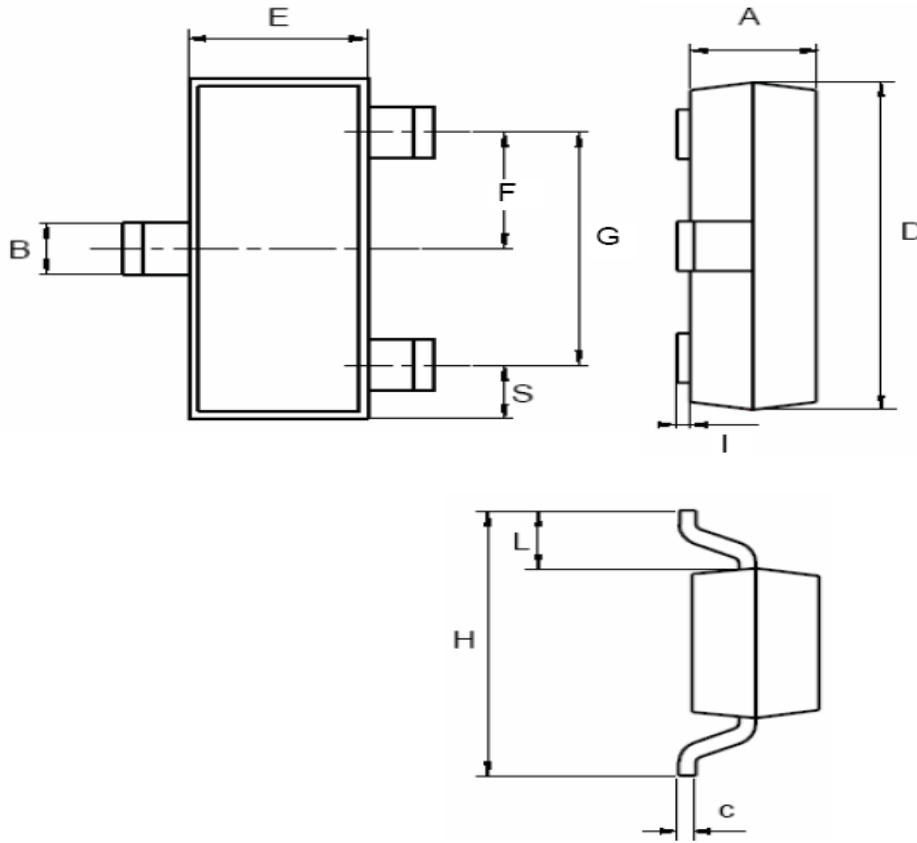


Figure 11. Capacitance

N-Channel 50V MOSFET



SOT-23		
DIM.	MIN.	MAX.
A	0.89	1.40
B	0.30	0.51
C	0.085	0.18
D	2.75	3.04
E	1.20	1.60
F	0.85	1.05
G	1.70	2.10
H	2.10	2.75
I	0.0	0.1
L	0.60 typ.	
S	0.35	0.65
All Dimensions in millimeter		

## **Important Notice and Disclaimer**

LSC reserves the right to make changes to this document and its products and specifications at any time without notice. Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.

LSC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does LSC assume any liability for application assistance or customer product design. LSC does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application.

No license is granted by implication or otherwise under any intellectual property rights of LSC.

LSC products are not authorized for use as critical components in life support devices or systems without express written approval of LSC.